# NPN Transistor with Zener Diode

#### Features

• These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Typical Applications**

- Driving Circuit
- Switching Applications

### **MAXIMUM RATINGS – NPN TRANSISTOR**

Symbol	Value	Unit
V <sub>CEO</sub>	40	V
V <sub>CBO</sub>	60	V
V <sub>EBO</sub>	6.0	V
Ι <sub>C</sub>	600	mA
I <sub>CM</sub>	900	mA
	V <sub>CEO</sub> V <sub>CBO</sub> V <sub>EBO</sub> I <sub>C</sub>	$\begin{array}{c c} V_{CEO} & 40 \\ V_{CBO} & 60 \\ V_{EBO} & 6.0 \\ I_{C} & 600 \\ \end{array}$

#### **MAXIMUM RATINGS - ZENER DIODE**

Rating	Symbol	Value	Unit
Forward Voltage @ I <sub>F</sub> = 10 mA	V <sub>F</sub>	0.9	V

## THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) @ T <sub>A</sub> = 25°C	PD	380	mW
Thermal Resistance from Junction-to-Ambient	$R_{\theta JA}$	328	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 Minimum Pad.



# **ON Semiconductor®**

http://onsemi.com

# NPN Transistor with Zener Diode





## MARKING DIAGRAM



(Note: Microdot may be in either location) \*Date Code orientation may vary depending upon manufacturing location.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSM6056MT1G	SC–74 (Pb–Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

### NPN TRANSISTOR – ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Cha	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS		•			•
Collector – Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	40	-	Vdc	
Collector – Base Breakdown Voltage	V <sub>(BR)CBO</sub>	60	-	Vdc	
Emitter-Base Breakdown Voltage	$(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	6.0	-	Vdc
Base Cutoff Current	$(V_{CE}$ = 35 Vdc, $V_{EB}$ = 0.4 Vdc)	I <sub>BEV</sub>	-	0.1	μAdc
Collector Cutoff Current	$(V_{CE}$ = 35 Vdc, $V_{EB}$ = 0.4 Vdc)	I <sub>CEX</sub>	-	0.1	μAdc
ON CHARACTERISTICS (Note 3)					
DC Current Gain		h <sub>FE</sub>	20 40 80 100 40	- - 300 -	-
Collector – Emitter Saturation Voltage	$(I_{C} = 150 \text{ mAdc}, I_{B} = 15 \text{ mAdc})$ $(I_{C} = 500 \text{ mAdc}, I_{B} = 50 \text{ mAdc})$	V <sub>CE(sat)</sub>		0.4 0.75	Vdc
Base – Emitter Saturation Voltage	V <sub>BE(sat)</sub>	0.75	0.95 1.2	Vdc	
SMALL-SIGNAL CHARACTERISTIC	S	•			·
Current-Gain - Bandwidth Product	(I <sub>C</sub> = 20 mAdc, V <sub>CE</sub> = 10 Vdc, f = 100 MHz)	f <sub>T</sub>	250	-	MHz
Collector-Base Capacitance	$(V_{CB} = 5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$	C <sub>cb</sub>	-	6.5	pF
Emitter-Base Capacitance	$(V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$	C <sub>eb</sub>	-	30	pF
Input Impedance	(I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 1.0 kHz)	h <sub>ie</sub>	1.0	15	kΩ
Voltage Feedback Ratio	(I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 1.0 kHz)	h <sub>re</sub>	0.1	8.0	X 10 <sup>-4</sup>
Small-Signal Current Gain	(I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 1.0 kHz)	h <sub>fe</sub>	40	500	-
Output Admittance	$(I_{C} = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h <sub>oe</sub>	1.0	30	μmhos
SWITCHING CHARACTERISTICS					
Delay Time	(V <sub>CC</sub> = 30 Vdc, V <sub>EB</sub> = 2.0 Vdc,	t <sub>d</sub>	-	15	
Rise Time	$I_{\rm C}$ = 150 mAdc, $I_{\rm B1}$ = 15 mAdc)	t <sub>r</sub>	-	20	ns
Storage Time	(V <sub>CC</sub> = 30 Vdc, I <sub>C</sub> = 150 mAdc,	t <sub>s</sub>	-	225	
Fall Time	I <sub>B1</sub> = I <sub>B2</sub> = 15 mAdc)	t <sub>f</sub>	-	30	ns

2. Pulse Test: Pulse Width  $\leq$  300  $\mu s,$  Duty Cycle  $\leq$  2.0%.

# **ZENER DIODE – ELECTRICAL CHARACTERISTICS** (V<sub>F</sub> = 0.9 Max @ $I_F$ = 10 mA for all types)

	Test	Zener Vo	ltage VZ	Z <sub>ZK</sub> I <sub>Z</sub> = 0.5	Z <sub>ZT</sub> I <sub>Z</sub> = IZT @ 10%	Ma IR @		d <sub>VZ</sub> /dt @ I <sub>ZT1</sub>		C pF Max @
Device	Current Izt mA	Min	Max	mA Ω Max	Mod Ω Max	μA	v	Min	Max	V <sub>R</sub> = 0 f = 1 MHz
NSM6056MT1G	5.0	5.49	5.73	200	40	1.0	2.0	-2.0	2.5	200

## **TYPICAL ELECTRICAL CHARACTERISTICS - NPN TRANSISTOR**













## **TYPICAL ELECTRICAL CHARACTERISTICS – NPN TRANSISTOR**



Figure 6. Current–Gain–Bandwidth Product







#### PACKAGE DIMENSIONS

**SC-74** CASE 318F-05 ISSUE M



NOTES:

- I. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  CONTROLLING DIMENSION: INCH
- CONTROLLING DIMENSION: INCH.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
- THICKNESS, MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

4.	318F-0	01, -02, -	03 OBSOL	ETE. NEV	V STANDARE	) 318F–04.

	м	ILLIMETE	RS		INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.37	0.50	0.010	0.015	0.020
С	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
е	0.85	0.95	1.05	0.034	0.037	0.041
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.75	3.00	0.099	0.108	0.118
θ	0°	-	10°	0°	-	10°

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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